**Board Characteristics**

1. All dimensions in mm, unless specified
2. Minimum trace width: 4 mils
3. 0.5 Oz Copper on all layers
5. Polyimide Coverlay (Kapton Soldermask) on Top and Bottom, as per Gerbers
6. Soft Au finish (ENIG) for Al wire bonding and hand soldering on all pads.
7. Place Stiffener on Top (Component) side of Flex PCB
8. Total flex circuit thickness cannot exceed 0.012", not including stiffener

**Layer Order**

- Film 1 - Component Side
- Film 2 - Signal 2
- Film 3 - Power
- Film 4 - Signal 3
- Film 5 - Bottom

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**Board’s Drill Schedule**

<table>
<thead>
<tr>
<th>Drill Symbol</th>
<th>Drill Size</th>
<th>Count</th>
<th>Plated</th>
<th>Tolerance</th>
<th>Comment</th>
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<tbody>
<tr>
<td>0</td>
<td>.00795</td>
<td>778</td>
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</tr>
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<td>.05</td>
<td>50</td>
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<td>.070866142</td>
<td>4</td>
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<td>---</td>
<td></td>
</tr>
<tr>
<td>3</td>
<td>.12</td>
<td>2</td>
<td>YES</td>
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</tbody>
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**UNIVERSITY OF CHICAGO ELECTRONICS DEVELOPMENT GROUP**

1Kx6K CCD Flex Rev. B
Specification Drawing
2935-B

- Drawn: M. Bogdan
- Checked: M. Bogdan
- Issue: 8/3/2021
- Date: 8/3/2021
- Thickness: 252.00
- Weight: 67.00